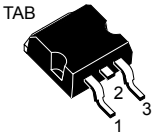
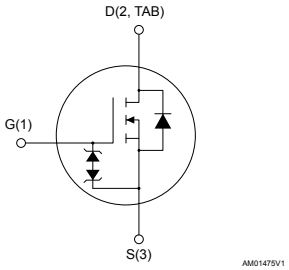
STB20N60M2-EP

Datasheet

N-channel 600 V, 0.230 Ω typ., 13 A MDmesh™ M2 EP Power MOSFET in a D²PAK package



D²PAK



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STB20N60M2-EP	600 V	0.278 Ω	13 A

- Extremely low gate charge
- Excellent output capacitance (C_{OSS}) profile
- Very low turn-off switching losses
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications
- Tailored for very high frequency converters (f > 150 kHz)

Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 enhanced performance (EP) technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance, optimized switching characteristics with very low turn-off switching losses, rendering it suitable for the most demanding very high frequency converters.

Product status link
STB20N60M2-EP

Product summary	
Order code	STB20N60M2-EP
Marking	20N60M2EP
Package	D²PAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_C = 25 °C	13	A
I_D	Drain current (continuous) at T_C = 100 °C	8	A
I_{DM} (1)	Drain current (pulsed)	52	A
P_{TOT}	Total dissipation at T_C = 25 °C	110	W
dv/dt(2)	Peak diode recovery voltage slope	15	V/ns
dv/dt(3)	MOSFET dv/dt ruggedness	50	V/ns
T_J	Operating junction temperature range	- 55 to 150	°C
T_{stg}	Storage temperature range		

1. *Pulse width limited by safe operating area.*
2. *I_{SD} ≤ 13 A, di/dt ≤ 400 A/µs; $V_{DS\ peak}$ < $V_{(BR)DSS}$, V_{DD} = 400 V.*
3. *V_{DS} ≤ 480 V*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	1.14	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	30	°C/W

1. *When mounted on FR-4 board of inch², 2 oz Cu.*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetetive or not repetitive (pulse width limited by T_{jmax})	2.7	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR}; V_{DD} = 50 V)	138	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	600			V
I_{DSS}	Zero gate voltage Drain current	V_{GS} = 0 V, V_{DS} = 600 V			1	µA
		V_{GS} = 0 V, V_{DS} = 600 V, T_C = 125 °C(1)			100	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3.25	4	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 6.5 A		0.230	0.278	Ω

1. *Defined by design, not subject to production test.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS}= 100 V, f = 1 MHz, V_{GS} = 0 V	-	787	-	pF
C_{oss}	Output capacitance		-	50	-	
C_{rss}	Reverse transfer capacitance		-	1.2	-	
$C_{oss\ eq.}$ (1)	Equivalent output capacitance	V_{DS} = 0 to 480 V, V_{GS} = 0 V	-	89	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz, I_D = 0 A	-	5.9	-	Ω
Q_g	Total gate charge	V_{DD} = 480 V, I_D = 13 A, V_{GS} = 0 to 10 V (see Figure 15. Test circuit for gate charge behavior)	-	22	-	nC
Q_{gs}	Gate-source charge		-	3.5	-	
Q_{gd}	Gate-drain charge		-	10.5	-	

1. *$C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}*

Table 6. Switching energy

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{off}	Turn-off energy (from 90% V_{GS} to 0% I_D)	V_{DD}= 400 V, I_D = 2 A, R_G= 4.7 Ω, V_{GS}= 10 V	-	7.2	-	µJ
		V_{DD}= 400 V, I_D = 5 A, R_G= 4.7 Ω, V_{GS}= 10 V	-	20.4	-	µJ

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 300 V, I_D = 6.5 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	10.5	-	ns
t_r	Rise time		-	5.2	-	ns
$t_{d(off)}$	Turn-off delay time		-	41	-	ns
t_f	Fall time		-	8	-	ns

Table 8. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		13	A
I_{SDM} (1)	Source-drain current (pulsed)		-		52	A
V_{SD} (2)	Forward on voltage	V_{GS} = 0 V, I_{SD} = 13 A	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 13 A, di/dt = 100 A/µs, V_{DD} = 60 V (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	230		ns
Q_{rr}	Reverse recovery charge		-	2.3		µC
I_{RRM}	Reverse recovery current		-	20		A
t_{rr}	Reverse recovery time	I_{SD} = 13 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_j = 150 °C (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	287		ns
Q_{rr}	Reverse recovery charge		-	2.9		µC
I_{RRM}	Reverse recovery current		-	20.2		A

1. *Pulse width is limited by safe operating area*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

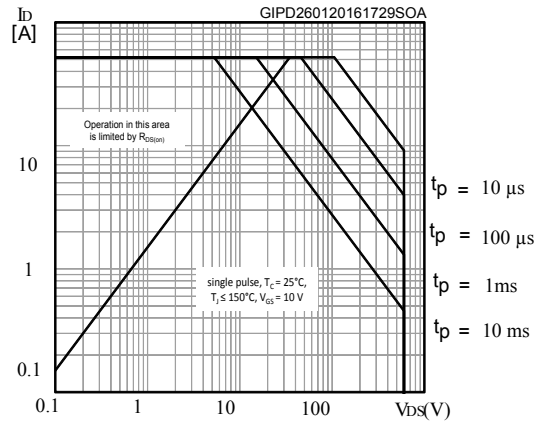


Figure 2. Thermal impedance

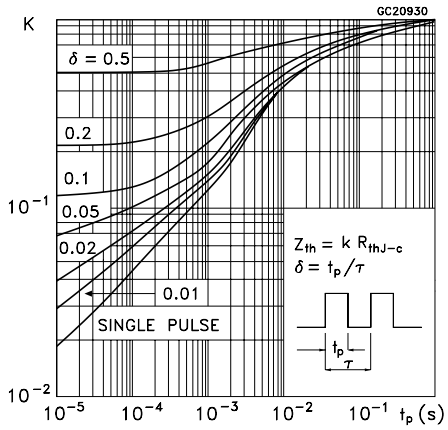


Figure 3. Output characteristics

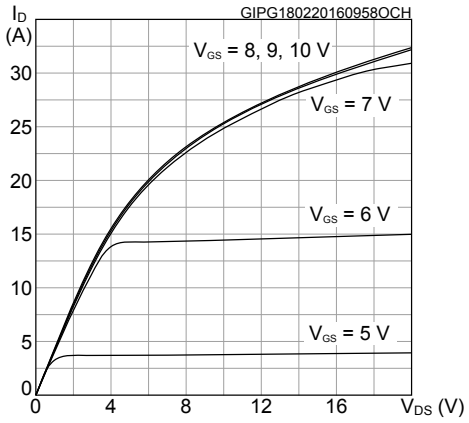


Figure 4. Transfer characteristics

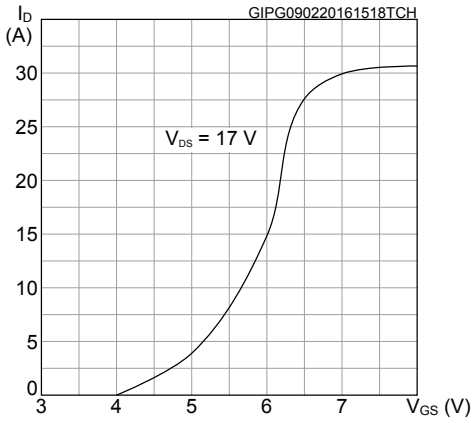


Figure 5. Gate charge vs gate-source voltage

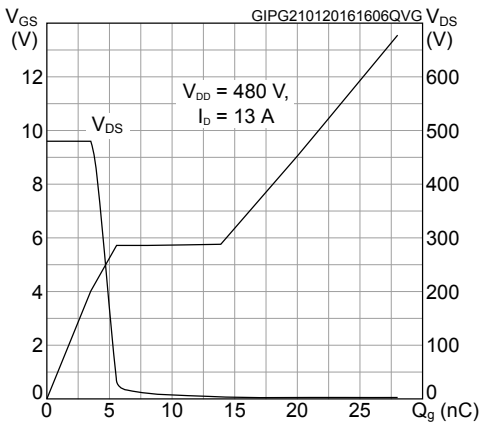


Figure 6. Static drain-source on-resistance

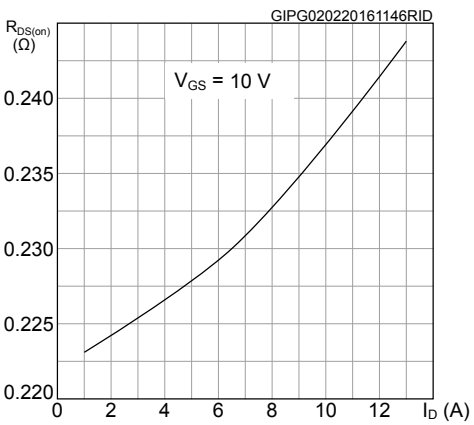


Figure 7. Capacitance variations

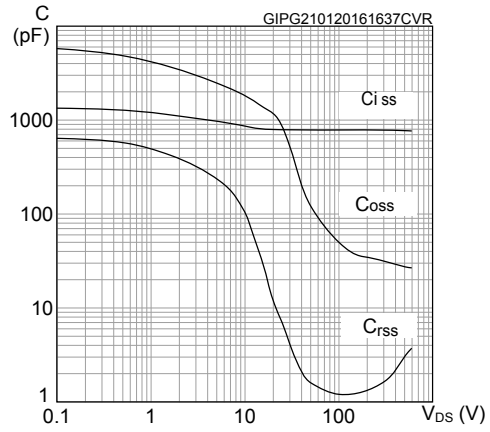


Figure 8. Output capacitance stored energy

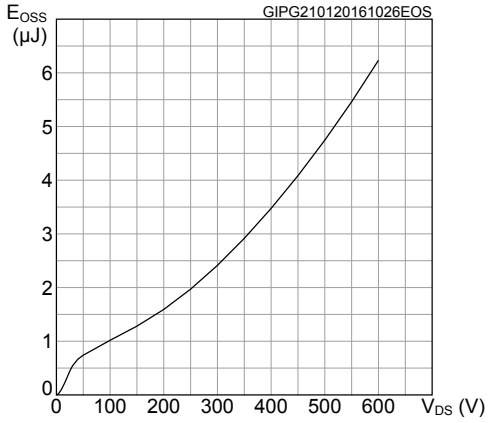


Figure 9. Normalized on-resistance vs temperature

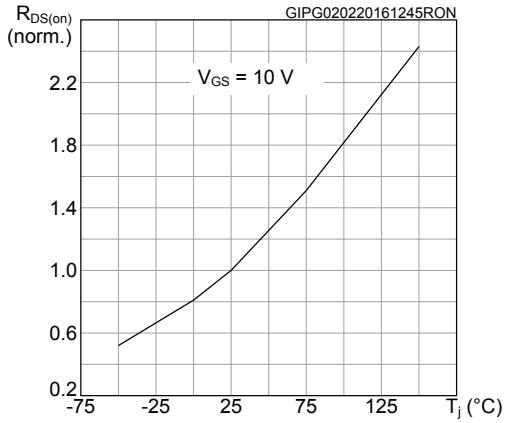


Figure 10. Normalized gate threshold voltage vs temperature

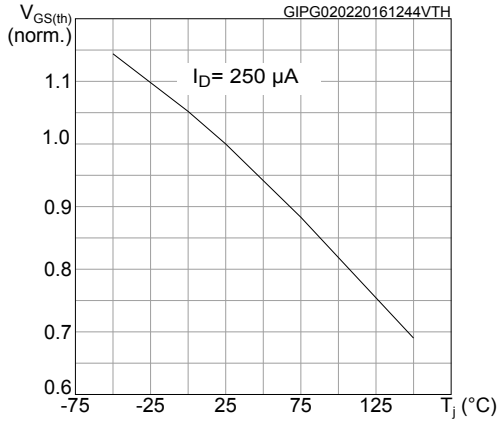


Figure 11. Normalized $V_{(BR)DSS}$ vs temperature

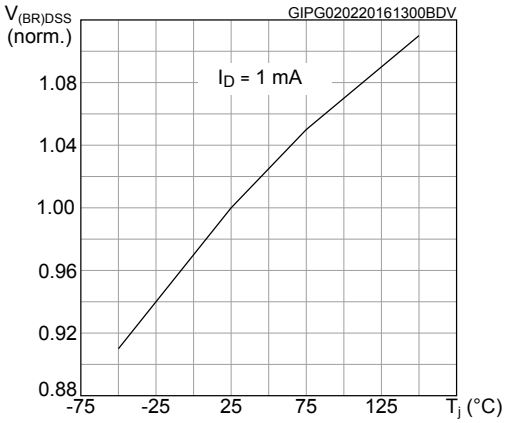


Figure 12. Source-drain diode forward characteristics

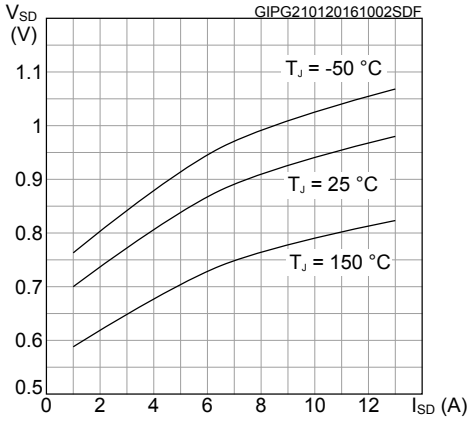
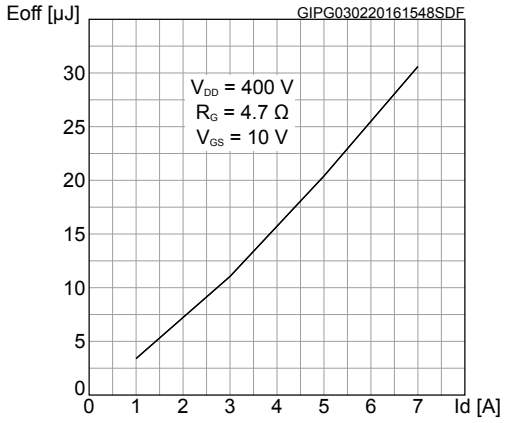


Figure 13. Turn-off switching energy vs drain current



3 Test circuits

Figure 14. Test circuit for resistive load switching times

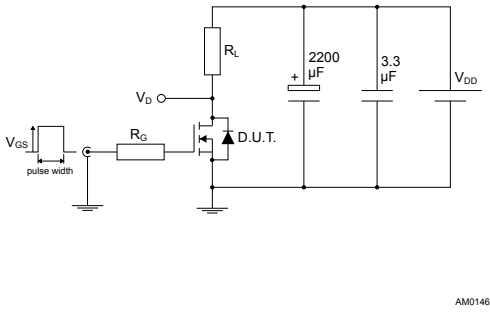


Figure 15. Test circuit for gate charge behavior

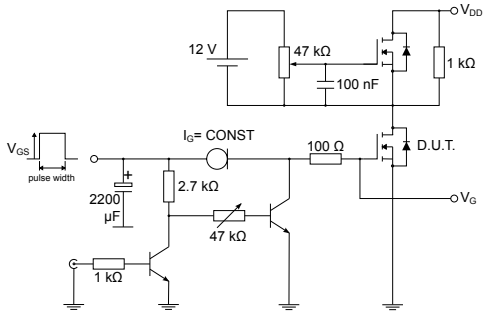


Figure 16. Test circuit for inductive load switching and diode recovery times

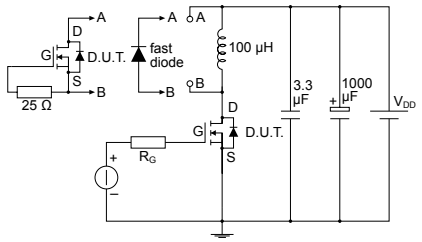


Figure 17. Unclamped inductive load test circuit

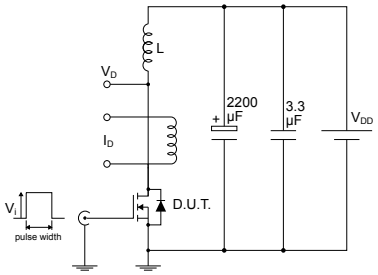


Figure 18. Unclamped inductive waveform

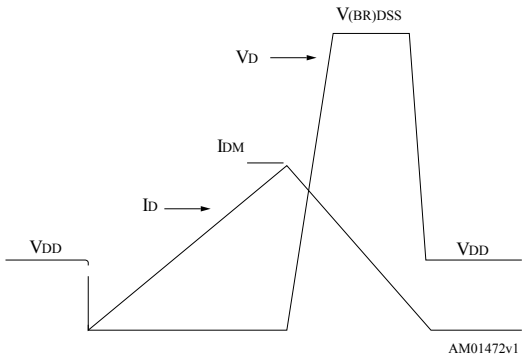
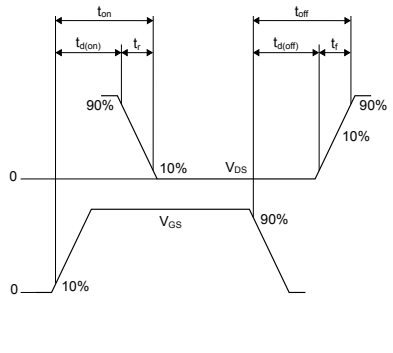


Figure 19. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-220 package information

Figure 20. D²PAK (TO-263) type A package outline

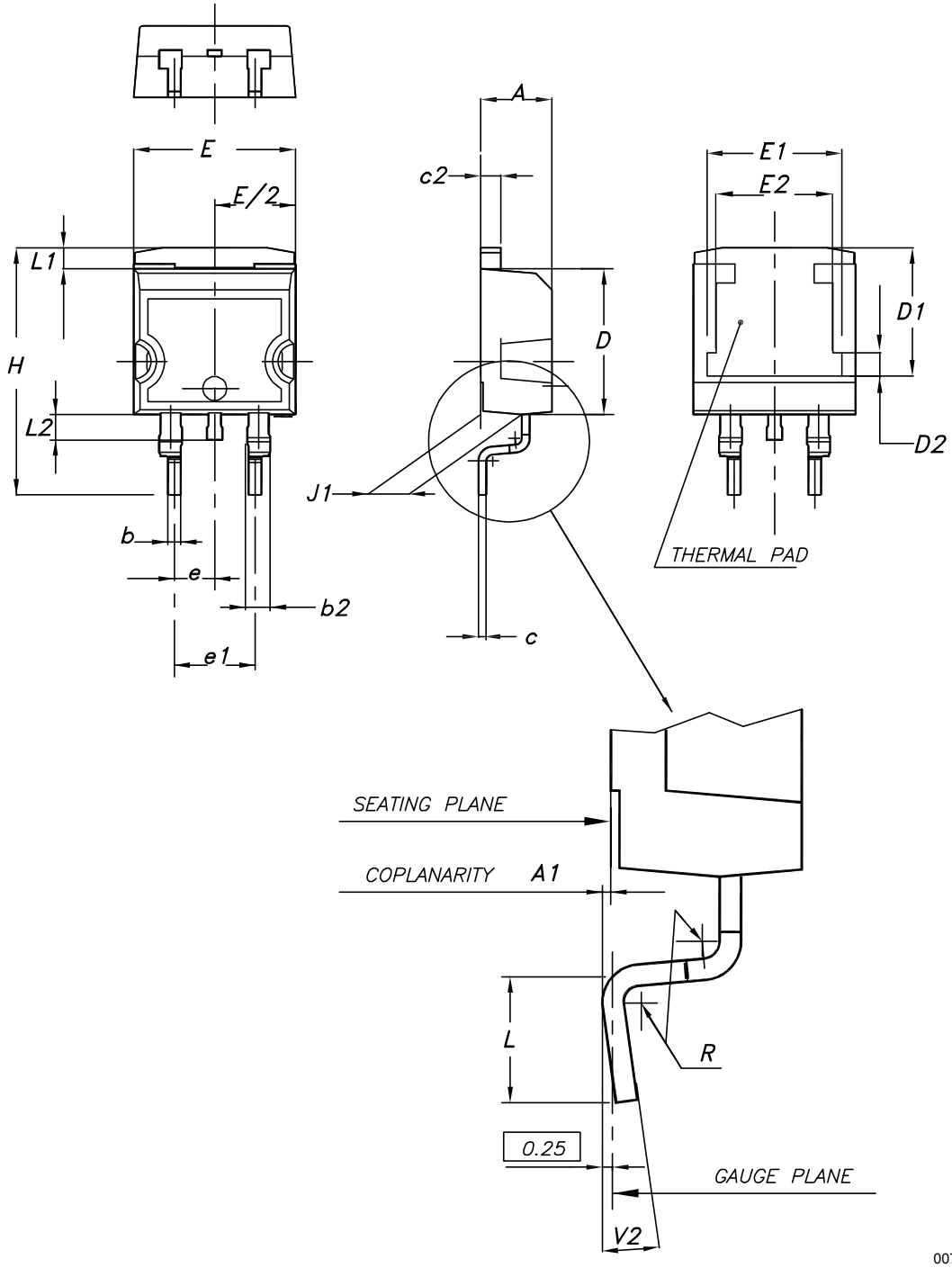
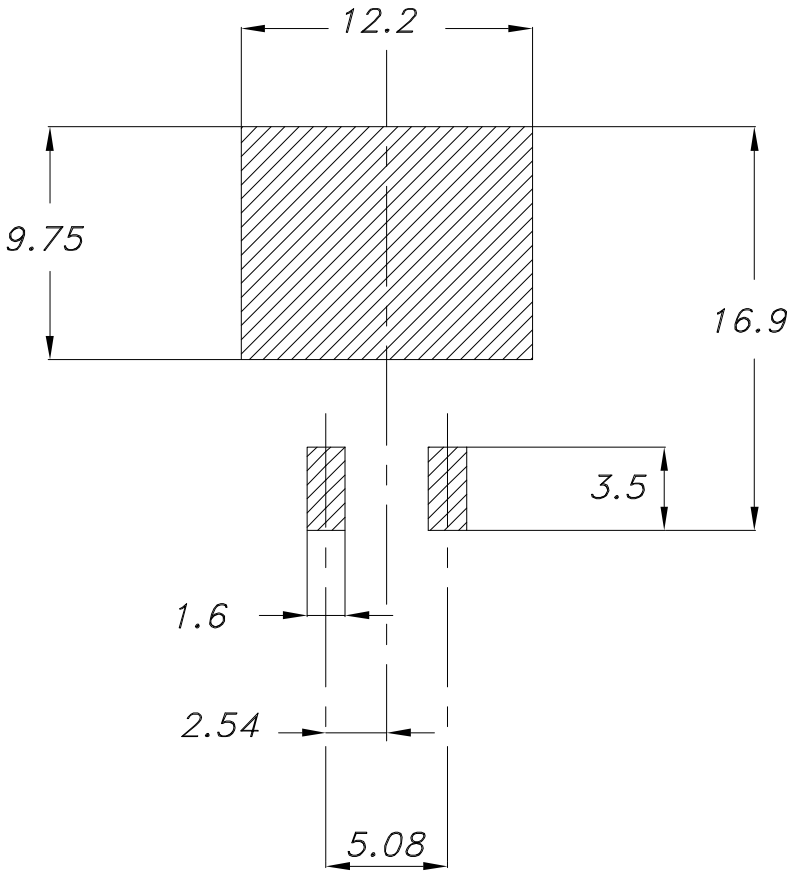


Table 9. D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 21. D²PAK (TO-263) recommended footprint (dimensions are in mm)



Footprint

4.2 D²PAK packing information

Figure 22. D²PAK tape outline

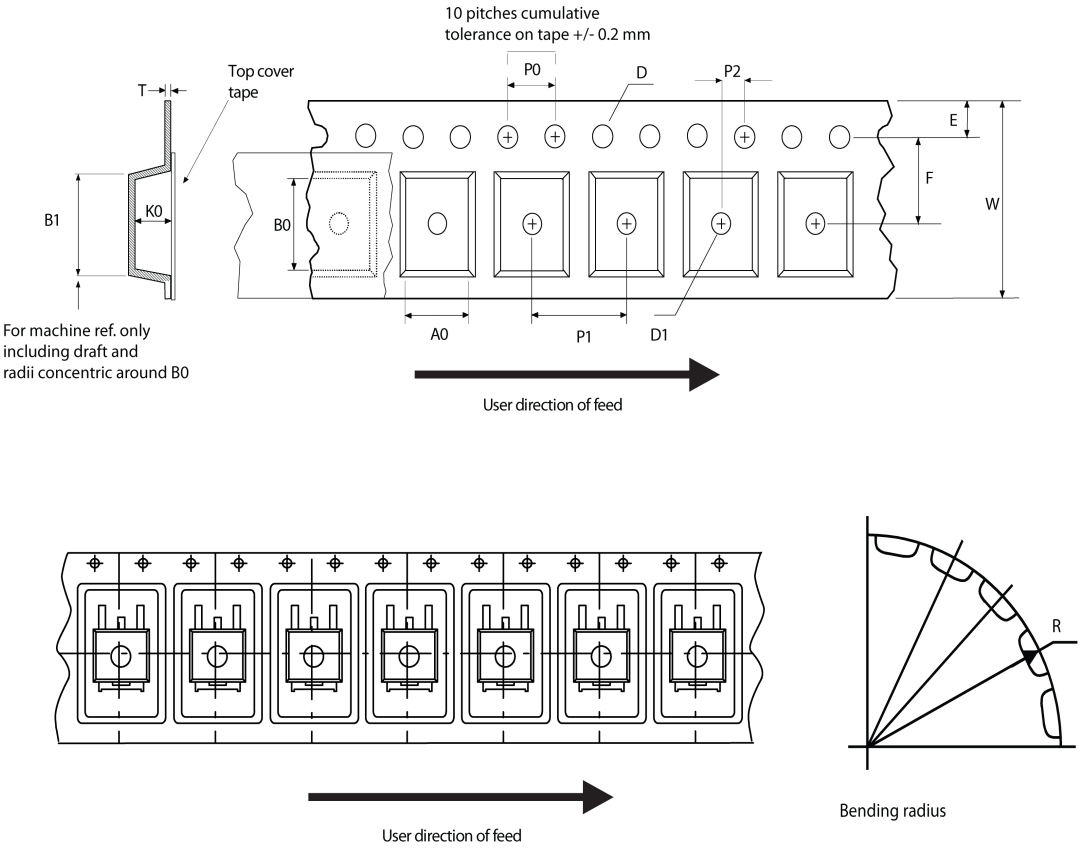


Figure 23. **D²PAK reel outline**

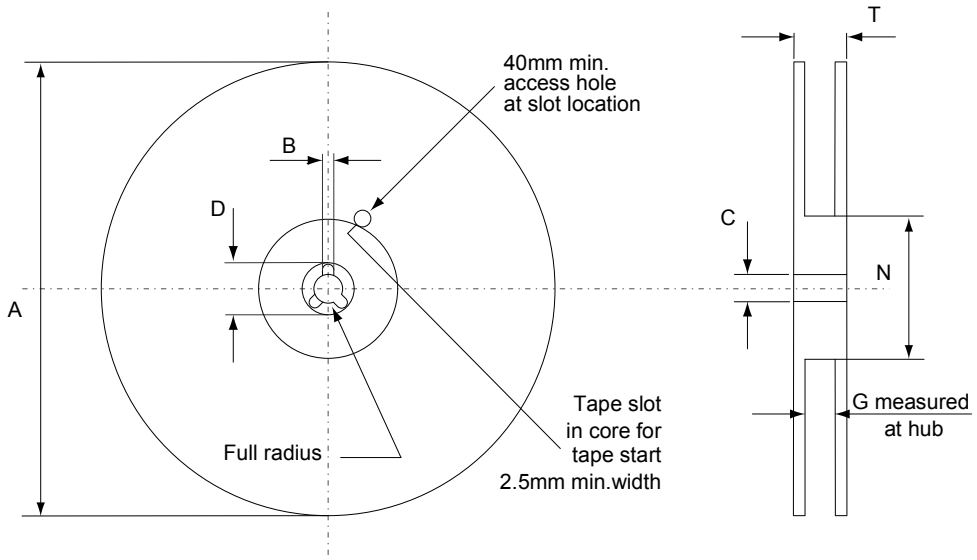


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Table 10. **D²PAK tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Revision history

Table 11. **Document revision history**

Date	Revision	Changes
11-Feb-2016	1	First release.
19-Mar-2018	2	Removed maturity status indication from cover page. The document status is production data. Updated *Section 1 Electrical ratings*, *Electrical characteristics* and *Electrical characteristics (curves)*. Minor text changes.
04-Jun-2018	3	Modified Table 1. Absolute maximum ratings and Table 8. Source-drain diode. Modified Figure 1. Safe operating area. Minor text changes.

Contents